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A semiconductor device includes: a semiconductor device main body; and an electrode terminal provided at a side of a main surface of the semiconductor device main body and partially protruding outward from the main surface, wherein the electrode terminal includes: a pillar layer made of copper and electrically connected to a wiring layer disposed within the semiconductor device main body; and a bonding layer formed over a surface of the pillar layer on an opposite side of the pillar layer from the wiring layer, and wherein the pillar layer includes: a disc-shaped first portion; and a columnar second portion formed over a central portion of a surface of the first portion on an opposite side of the first portion from the wiring layer.

